

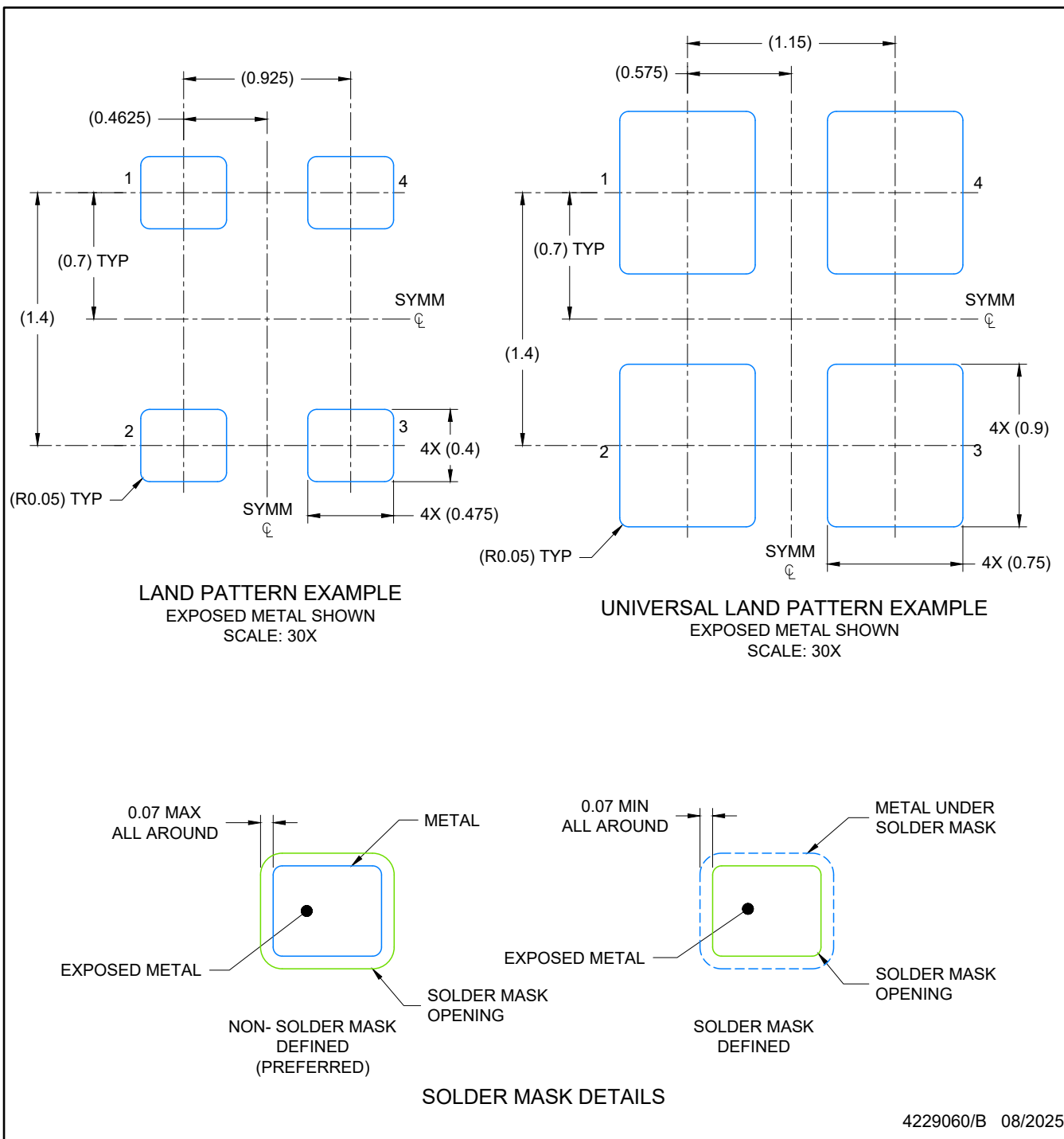
PACKAGE OUTLINE

VSON - 1 mm max height

The drawing illustrates the geometry of a connector housing with the following details:

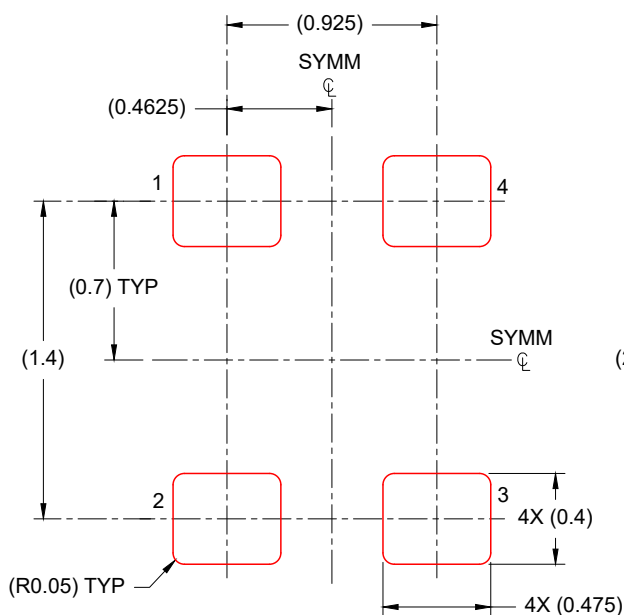
- Front View (Top):** Shows a rectangular housing with a width of 1.7 (1.5) and a height of 2.1 (1.9). A shaded region on the left is labeled "PIN 1 INDEX AREA".
- Side View (Middle):** Shows the housing's profile with a height of 1.0 (0.8). A "SEATING PLANE" is indicated at the base. A feature callout shows a semi-circular profile with a radius of 0.08 and a center point C.
- Top View (Bottom):** Shows the housing from above with a width of 0.925 and a height of 0.4625. It features four rectangular pin locations arranged in a 2x2 grid. A vertical centerline is labeled "SYMM". A feature callout shows a rectangular profile with a width of 0.08 and a center point C.
- Detail View (Bottom Right):** A magnified view of the pin locations, showing a width of 0.14 TYP.
- Feature Callouts:**
 - "PIN 1 ID (OPTIONAL)" points to a specific pin location.
 - "4X 0.45 0.35" indicates four holes with a diameter of 0.45 and a depth of 0.35.
 - "4X 0.52 0.42" indicates four holes with a diameter of 0.52 and a depth of 0.42.
 - "0.1 (M) C A B" and "0.05 (M) C" are feature callouts for specific holes.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

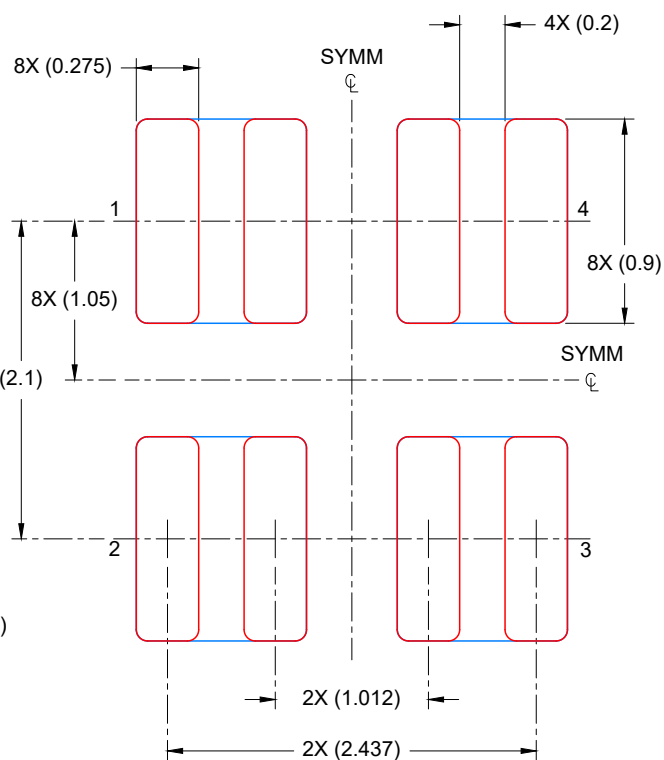


NOTES: (continued)

- For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271) .



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE: 20X



UNIVERSAL SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE: 20X

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
 ALL PADS: 73%

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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